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Assistant Commissioner for Patents,
Washington, D.C., 20231, on 3/31/03

Deborah W. Wenocur

#17
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3/31/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant:	K. Sahota, D. Schonauer, J. Groschopf,) G. Marxsen, and S. Avanzino,)	Grp Art Unit: 1765))
Assignee:	Advanced Micro Devices, Inc.	Exam: L. Umez Eronini))
Serial Number:	09/749,191))
Filed:	December 26, 2000))
For:	PREVENTION OF PRECIPITATION) DEFECTS ON COPPER INTER-) CONNECTS DURING CMP BY USE) OF SOLUTIONS CONTAINING) ORGANIC COMPOUNDS WITH) SILICA ADSORPTION AND COPPER) CORROSION INHIBITING) PROPERTIES))	

Assistant Commissioner for Patents

Washington, D.C. 20231

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RESPONSE TO OFFICE ACTION

Dear Sir,

This is in response to the Office Action mailed on December 19, 2002.